



CBR-SMD RF COG, Ceramic, 2.9 pF, +/-0.1 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

2.9 pF

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

W 0.5mm +/-0.05mm Voltage DC 50 VDC	
T 0.5mm +/-0.05mm Dielectric Withstanding Voltage 125 VDC	
B 0.25mm +0.05/-0.1mm Temperature Range -55/+125°C	
Temp. Coefficient COG	
Packaging Specifications Dissipation Factor 0.218%	
Packaging T&R, 180mm, Plastic Tape Aging Rate 0% Loss/Decade Hour	
Packaging Quantity 10000 Insulation Resistance 10 GOhms	
Quality Factor 458	
Packaging T&P 180mm Plastic Tape	

Specifications Capacitance

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